

LM340/LM78XX Series 3-Terminal Positive Regulators

Check for Samples: [LM340-N](#)

FEATURES

- Complete specifications at 1A load
- Output voltage tolerances of $\pm 2\%$ at $T_j = 25^\circ\text{C}$ and $\pm 4\%$ over the temperature range (LM340A)
- Line regulation of 0.01% of V_{OUT}/V of ΔV_{IN} at 1A load (LM340A)
- Load regulation of 0.3% of V_{OUT}/A (LM340A)
- Internal thermal overload protection
- Internal short-circuit current limit
- Output transistor safe area protection
- P⁺ Product Enhancement tested

DESCRIPTION

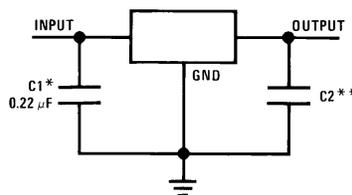
The LM140/LM340A/LM340/LM78XXC monolithic 3-terminal positive voltage regulators employ internal current-limiting, thermal shutdown and safe-area compensation, making them essentially indestructible. If adequate heat sinking is provided, they can deliver over 1.0A output current. They are intended as fixed voltage regulators in a wide range of applications including local (on-card) regulation for elimination of noise and distribution problems associated with single-point regulation. In addition to use as fixed voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents.

Considerable effort was expended to make the entire series of regulators easy to use and minimize the number of external components. It is not necessary to bypass the output, although this does improve transient response. Input bypassing is needed only if the regulator is located far from the filter capacitor of the power supply.

The 5V, 12V, and 15V regulator options are available in the steel TO-3 power package. The LM340A/LM340/LM78XXC series is available in the TO-220 plastic power package, and the LM340-5.0 is available in the SOT-223 package, as well as the LM340-5.0 and LM340-12 in the surface-mount TO-263 package.

Typical Applications

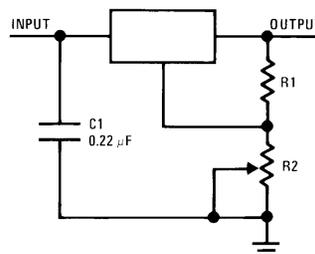
Figure 1. Fixed Output Regulator



*Required if the regulator is located far from the power supply filter.

**Although no output capacitor is needed for stability, it does help transient response. (If needed, use 0.1 μF , ceramic disc).

Figure 2. Adjustable Output Regulator



$$V_{\text{OUT}} = 5V + (5V/R1 + I_Q) R2 \quad 5V/R1 > 3 I_Q$$

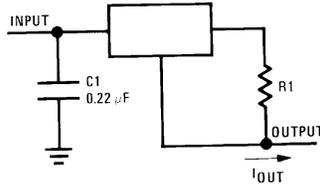
load regulation (L_r) $\approx [(R1 + R2)/R1]$ (L_r of LM340-5).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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Figure 3. Current Regulator



$$I_{OUT} = \frac{V_{2-3}}{R1} + I_Q$$

$\Delta I_Q = 1.3 \text{ mA}$ over line and load changes.

Comparison between SOT-223 and D-Pak (TO-252) Packages

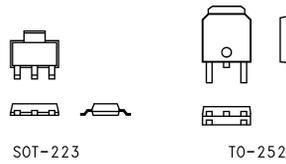


Figure 4. Scale 1:1

Connection Diagrams

TO-3 Metal Can Package (K)

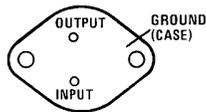


Figure 5. Bottom View

TO-220 Power Package (T)

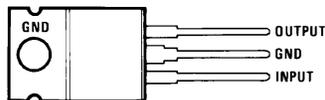


Figure 6. Top View

TO-263 Surface-Mount Package (S)

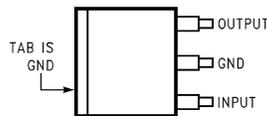


Figure 7. Top View

3-Lead SOT-223

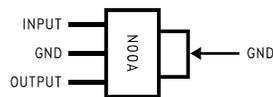


Figure 8. Top View



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ^{(1) (2)}

DC Input Voltage	35V
Internal Power Dissipation ⁽³⁾	Internally Limited
Maximum Junction Temperature	150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 10 sec.)	
TO-3 Package (K)	300°C
TO-220 Package (T), TO-263 Package (S)	230°C
ESD Susceptibility ⁽⁴⁾	2 kV

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Conditions are conditions under which the device functions but the specifications might not be guaranteed. For guaranteed specifications and test conditions see the Electrical Characteristics.
- (2) Military datasheets are available upon request. At the time of printing, the military datasheet specifications for the LM140K-5.0/883, LM140K-12/883, and LM140K-15/883 complied with the min and max limits for the respective versions of the LM140. The LM140H and LM140K may also be procured as JAN devices on slash sheet JM38510/107.
- (3) The maximum allowable power dissipation at any ambient temperature is a function of the maximum junction temperature for operation ($T_{JMAX} = 125^{\circ}\text{C}$ or 150°C), the junction-to-ambient thermal resistance (θ_{JA}), and the ambient temperature (T_A). $P_{DMAX} = (T_{JMAX} - T_A)/\theta_{JA}$. If this dissipation is exceeded, the die temperature will rise above T_{JMAX} and the electrical specifications do not apply. If the die temperature rises above 150°C , the device will go into thermal shutdown. For the TO-3 package (K, KC), the junction-to-ambient thermal resistance (θ_{JA}) is $39^{\circ}\text{C}/\text{W}$. When using a heatsink, θ_{JA} is the sum of the $4^{\circ}\text{C}/\text{W}$ junction-to-case thermal resistance (θ_{JC}) of the TO-3 package and the case-to-ambient thermal resistance of the heatsink. For the TO-220 package (T), θ_{JA} is $54^{\circ}\text{C}/\text{W}$ and θ_{JC} is $4^{\circ}\text{C}/\text{W}$. If SOT-223 is used, the junction-to-ambient thermal resistance is $174^{\circ}\text{C}/\text{W}$ and can be reduced by a heatsink (see Applications Hints on heatsinking). If the TO-263 package is used, the thermal resistance can be reduced by increasing the PC board copper area thermally connected to the package: Using 0.5 square inches of copper area, θ_{JA} is $50^{\circ}\text{C}/\text{W}$; with 1 square inch of copper area, θ_{JA} is $37^{\circ}\text{C}/\text{W}$; and with 1.6 or more inches of copper area, θ_{JA} is $32^{\circ}\text{C}/\text{W}$.
- (4) ESD rating is based on the human body model, 100 pF discharged through 1.5 k Ω .

Operating Conditions ⁽¹⁾

Temperature Range (T_A) ⁽²⁾	
LM140	-55°C to +125°C
LM340A, LM340	0°C to +125°C
LM7808C	0°C to +125°C

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Conditions are conditions under which the device functions but the specifications might not be guaranteed. For guaranteed specifications and test conditions see the Electrical Characteristics.
- (2) The maximum allowable power dissipation at any ambient temperature is a function of the maximum junction temperature for operation ($T_{JMAX} = 125^{\circ}\text{C}$ or 150°C), the junction-to-ambient thermal resistance (θ_{JA}), and the ambient temperature (T_A). $P_{DMAX} = (T_{JMAX} - T_A)/\theta_{JA}$. If this dissipation is exceeded, the die temperature will rise above T_{JMAX} and the electrical specifications do not apply. If the die temperature rises above 150°C , the device will go into thermal shutdown. For the TO-3 package (K, KC), the junction-to-ambient thermal resistance (θ_{JA}) is $39^{\circ}\text{C}/\text{W}$. When using a heatsink, θ_{JA} is the sum of the $4^{\circ}\text{C}/\text{W}$ junction-to-case thermal resistance (θ_{JC}) of the TO-3 package and the case-to-ambient thermal resistance of the heatsink. For the TO-220 package (T), θ_{JA} is $54^{\circ}\text{C}/\text{W}$ and θ_{JC} is $4^{\circ}\text{C}/\text{W}$. If SOT-223 is used, the junction-to-ambient thermal resistance is $174^{\circ}\text{C}/\text{W}$ and can be reduced by a heatsink (see Applications Hints on heatsinking). If the TO-263 package is used, the thermal resistance can be reduced by increasing the PC board copper area thermally connected to the package: Using 0.5 square inches of copper area, θ_{JA} is $50^{\circ}\text{C}/\text{W}$; with 1 square inch of copper area, θ_{JA} is $37^{\circ}\text{C}/\text{W}$; and with 1.6 or more inches of copper area, θ_{JA} is $32^{\circ}\text{C}/\text{W}$.

LM340A Electrical Characteristics

$I_{OUT} = 1A$, $0^{\circ}C \leq T_J \leq +125^{\circ}C$ (LM340A) unless otherwise specified ⁽¹⁾

Symbol	Output Voltage		5V			12V			15V			Units
	Input Voltage (unless otherwise noted)	Conditions	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_O	Output Voltage	$T_J = 25^{\circ}C$	4.9	5	5.1	11.75	12	12.25	14.7	15	15.3	V
		$P_D \leq 15W$, $5 mA \leq I_O \leq 1A$	4.8		5.2	11.5		12.5	14.4		15.6	V
ΔV_O	Line Regulation	$V_{MIN} \leq V_{IN} \leq V_{MAX}$	(7.5 $\leq V_{IN} \leq 20$)			(14.8 $\leq V_{IN} \leq 27$)			(17.9 $\leq V_{IN} \leq 30$)			V
		$I_O = 500 mA$			10			18			22	mV
ΔV_O	Line Regulation	ΔV_{IN}	(7.5 $\leq V_{IN} \leq 20$)			(14.8 $\leq V_{IN} \leq 27$)			(17.9 $\leq V_{IN} \leq 30$)			V
		$T_J = 25^{\circ}C$		3	10		4	18		4	22	mV
ΔV_O	Line Regulation	ΔV_{IN}	(7.5 $\leq V_{IN} \leq 20$)			(14.5 $\leq V_{IN} \leq 27$)			(17.5 $\leq V_{IN} \leq 30$)			V
		$T_J = 25^{\circ}C$			4			9			10	mV
ΔV_O	Line Regulation	Over Temperature			12			30			30	mV
		ΔV_{IN}	(8 $\leq V_{IN} \leq 12$)			(16 $\leq V_{IN} \leq 22$)			(20 $\leq V_{IN} \leq 26$)			V
ΔV_O	Load Regulation	$T_J = 25^{\circ}C$	5 mA $\leq I_O \leq 1.5A$	10	25		12	32		12	35	mV
					15		19		21	mV		
ΔV_O	Load Regulation	Over Temperature,		25			60			75	mV	
		5 mA $\leq I_O \leq 1A$										
I_Q	Quiescent Current	$T_J = 25^{\circ}C$			6			6			6	mA
		Over Temperature			6.5			6.5			6.5	mA
ΔI_Q	Quiescent Current	5 mA $\leq I_O \leq 1A$		0.5			0.5			0.5		mA
		Change	$T_J = 25^{\circ}C$, $I_O = 1A$			0.8			0.8			0.8
ΔV_O	Line Regulation	$V_{MIN} \leq V_{IN} \leq V_{MAX}$	(7.5 $\leq V_{IN} \leq 20$)			(14.8 $\leq V_{IN} \leq 27$)			(17.9 $\leq V_{IN} \leq 30$)			V
		$I_O = 500 mA$			0.8			0.8			0.8	mA
V_N	Output Noise Voltage	$V_{MIN} \leq V_{IN} \leq V_{MAX}$	(8 $\leq V_{IN} \leq 25$)			(15 $\leq V_{IN} \leq 30$)			(17.9 $\leq V_{IN} \leq 30$)			V
		$T_A = 25^{\circ}C$, 10 Hz $\leq f \leq 100$ kHz		40			75			90		μV
$\frac{\Delta V_{IN}}{\Delta V_{OUT}}$	Ripple Rejection	$T_J = 25^{\circ}C$, $f = 120$ Hz, $I_O = 1A$	68	80		61	72		60	70		dB
		or $f = 120$ Hz, $I_O = 500 mA$,	68			61			60			dB
R_O	Dropout Voltage	Over Temperature,										
		$V_{MIN} \leq V_{IN} \leq V_{MAX}$	(8 $\leq V_{IN} \leq 18$)			(15 $\leq V_{IN} \leq 25$)			(18.5 $\leq V_{IN} \leq 28.5$)			V
R_O	Dropout Voltage	$T_J = 25^{\circ}C$, $I_O = 1A$		2.0			2.0			2.0		V
		Output Resistance	$f = 1$ kHz		8			18			19	m Ω
R_O	Dropout Voltage	Short-Circuit Current	$T_J = 25^{\circ}C$		2.1			1.5			1.2	A
		Peak Output Current	$T_J = 25^{\circ}C$		2.4			2.4			2.4	A
R_O	Dropout Voltage	Average TC of V_O	Min, $T_J = 0^{\circ}C$, $I_O = 5 mA$		-0.6			-1.5			-1.8	mV/ $^{\circ}C$
		Input Voltage	$T_J = 25^{\circ}C$									

(1) All characteristics are measured with a 0.22 μF capacitor from input to ground and a 0.1 μF capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques ($t_w \leq 10$ ms, duty cycle $\leq 5\%$). Output voltage changes due to changes in internal temperature must be taken into account separately.

LM340A Electrical Characteristics (continued)
 $I_{OUT} = 1A, 0^{\circ}C \leq T_J \leq +125^{\circ}C$ (LM340A) unless otherwise specified ⁽¹⁾

	Output Voltage		5V			12V			15V				
Symbol	Input Voltage (unless otherwise noted)		10V			19V			23V			Units	
	Parameter	Conditions		Min	Typ	Ma x	Min	Typ	Max	Min	Typ	Max	
	Required to Maintain			7.5			14.5			17.5			V
	Line Regulation												

LM140 Electrical Characteristics ⁽¹⁾

–55°C ≤ T_J ≤ +150°C unless otherwise specified

Symbol	Output Voltage		5V			12V			15V			Units
	Input Voltage (unless otherwise noted)		10V			19V			23V			
	Parameter	Conditions		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
V _O	Output Voltage	T _J = 25°C, 5 mA ≤ I _O ≤ 1A		4.8	5	5.2	11.5	12	12.5	14.4	15	15.6
		P _D ≤ 15W, 5 mA ≤ I _O ≤ 1A		4.75		5.25	11.4		12.6	14.25		15.75
		V _{MIN} ≤ V _{IN} ≤ V _{MAX}		(8 ≤ V _{IN} ≤ 20)			(15.5 ≤ V _{IN} ≤ 27)			(18.5 ≤ V _{IN} ≤ 30)		
ΔV _O	Line Regulation	I _O = 500 mA	T _J = 25°C		3	50		4	120		4	150
			ΔV _{IN}	(7 ≤ V _{IN} ≤ 25)			(14.5 ≤ V _{IN} ≤ 30)			(17.5 ≤ V _{IN} ≤ 30)		
			–55°C ≤ T _J ≤ +150°C			50			120			150
			ΔV _{IN}	(8 ≤ V _{IN} ≤ 20)			(15 ≤ V _{IN} ≤ 27)			(18.5 ≤ V _{IN} ≤ 30)		
		I _O ≤ 1A	T _J = 25°C			50			120			150
			ΔV _{IN}	(7.5 ≤ V _{IN} ≤ 20)			(14.6 ≤ V _{IN} ≤ 27)			(17.7 ≤ V _{IN} ≤ 30)		
			–55°C ≤ T _J ≤ +150°C			25			60			75
			ΔV _{IN}	(8 ≤ V _{IN} ≤ 12)			(16 ≤ V _{IN} ≤ 22)			(20 ≤ V _{IN} ≤ 26)		
ΔV _O	Load Regulation	T _J = 25°C	5 mA ≤ I _O ≤ 1.5A		10	50		12	120		12	150
			250 mA ≤ I _P ≤ 750 mA			25			60			75
		–55°C ≤ T _J ≤ +150°C,				50			120			150
		5 mA ≤ I _O ≤ 1A										
I _Q	Quiescent Current	I _O ≤ 1A	T _J = 25°C			6			6			6
			–55°C ≤ T _J ≤ +150°C			7			7			7
ΔI _Q	Quiescent Current Change	5 mA ≤ I _O ≤ 1A			0.5			0.5			0.5	
		T _J = 25°C, I _O ≤ 1A				0.8			0.8			0.8
		V _{MIN} ≤ V _{IN} ≤ V _{MAX}		(8 ≤ V _{IN} ≤ 20)			(15 ≤ V _{IN} ≤ 27)			(18.5 ≤ V _{IN} ≤ 30)		
		I _O = 500 mA, –55°C ≤ T _J ≤ +150°C				0.8			0.8			0.8
		V _{MIN} ≤ V _{IN} ≤ V _{MAX}		(8 ≤ V _{IN} ≤ 25)			(15 ≤ V _{IN} ≤ 30)			(18.5 ≤ V _{IN} ≤ 30)		
V _N	Output Noise Voltage	T _A = 25°C, 10 Hz ≤ f ≤ 100 kHz			40			75			90	
ΔV _{IN} / ΔV _{OUT}	Ripple Rejection	I _O ≤ 1A, T _J = 25°C or		68	80		61	72		60	70	
		f = 120 Hz, I _O ≤ 500 mA,		68			61			60		
		–55°C ≤ T _J ≤ +150°C										
		V _{MIN} ≤ V _{IN} ≤ V _{MAX}		(8 ≤ V _{IN} ≤ 18)			(15 ≤ V _{IN} ≤ 25)			(18.5 ≤ V _{IN} ≤ 28.5)		
R _O	Dropout Voltage	T _J = 25°C, I _O = 1A			2.0			2.0			2.0	
	Output Resistance	f = 1 kHz			8			18			19	
	Short-Circuit Current	T _J = 25°C			2.1			1.5			1.2	

(1) All characteristics are measured with a 0.22 μF capacitor from input to ground and a 0.1 μF capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.

LM140 Electrical Characteristics ⁽¹⁾ (continued)
 $-55^{\circ}\text{C} \leq T_J \leq +150^{\circ}\text{C}$ unless otherwise specified

	Output Voltage		5V			12V			15V			
Symbol	Input Voltage (unless otherwise noted)		10V			19V			23V			Units
	Parameter	Conditions	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	Peak Output Current	$T_J = 25^{\circ}\text{C}$		2.4			2.4			2.4		A
	Average TC of V_{OUT}	$0^{\circ}\text{C} \leq T_J \leq +150^{\circ}\text{C}$, $I_O = 5\text{ mA}$		-0.6			-1.5			-1.8		mV/ $^{\circ}\text{C}$
V_{IN}	Input Voltage	$T_J = 25^{\circ}\text{C}$, $I_O \leq 1\text{ A}$										
	Required to Maintain		7.5			14.6			17.7			V
	Line Regulation											

LM340 Electrical Characteristics ⁽¹⁾ (continued)
 $0^{\circ}\text{C} \leq T_J \leq +125^{\circ}\text{C}$ unless otherwise specified

	Output Voltage		5V			12V			15V			
Symbol	Input Voltage (unless otherwise noted)		10V			19V			23V			Units
	Parameter	Conditions	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	Average TC of V_{OUT}	$0^{\circ}\text{C} \leq T_J \leq +125^{\circ}\text{C}$, $I_O = 5\text{ mA}$		-0.6			-1.5			-1.8		mV/°C
V_{IN}	Input Voltage	$T_J = 25^{\circ}\text{C}$, $I_O \leq 1\text{ A}$										
	Required to Maintain		7.5			14.6			17.7			V
	Line Regulation											

LM7808C

Electrical Characteristics

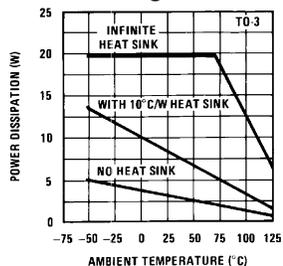
$0^{\circ}\text{C} \leq T_J \leq +150^{\circ}\text{C}$, $V_I = 14\text{V}$, $I_O = 500\text{ mA}$, $C_I = 0.33\text{ }\mu\text{F}$, $C_O = 0.1\text{ }\mu\text{F}$, unless otherwise specified

Symbol	Parameter		Conditions ⁽¹⁾		LM7808C			Units
					Min	Typ	Max	
V_O	Output Voltage		$T_J = 25^{\circ}\text{C}$		7.7	8.0	8.3	V
ΔV_O	Line Regulation		$T_J = 25^{\circ}\text{C}$			6.0	160	mV
						2.0	80	
ΔV_O	Load Regulation		$T_J = 25^{\circ}\text{C}$			12	160	mV
						4.0	80	
V_O	Output Voltage		$11.5\text{V} \leq V_I \leq 23\text{V}$, $5.0\text{ mA} \leq I_O \leq 1.0\text{A}$, $P \leq 15\text{W}$		7.6		8.4	V
I_Q	Quiescent Current		$T_J = 25^{\circ}\text{C}$			4.3	8.0	mA
ΔI_Q	Quiescent	With Line	$11.5\text{V} \leq V_I \leq 25\text{V}$				1.0	mA
	Current Change	With Load	$5.0\text{ mA} \leq I_O \leq 1.0\text{A}$				0.5	
V_N	Noise		$T_A = 25^{\circ}\text{C}$, $10\text{ Hz} \leq f \leq 100\text{ kHz}$			52		μV
$\Delta V_I/\Delta V_O$	Ripple Rejection		$f = 120\text{ Hz}$, $I_O = 350\text{ mA}$, $T_J = 25^{\circ}\text{C}$		56	72		dB
V_{DO}	Dropout Voltage		$I_O = 1.0\text{A}$, $T_J = 25^{\circ}\text{C}$			2.0		V
R_O	Output Resistance		$f = 1.0\text{ kHz}$			16		$\text{m}\Omega$
I_{OS}	Output Short Circuit Current		$T_J = 25^{\circ}\text{C}$, $V_I = 35\text{V}$			0.45		A
I_{PK}	Peak Output Current		$T_J = 25^{\circ}\text{C}$			2.2		A
$\Delta V_O/\Delta T$	Average Temperature		$I_O = 5.0\text{ mA}$			0.8		$\text{mV}/^{\circ}\text{C}$
	Coefficient of Output Voltage							

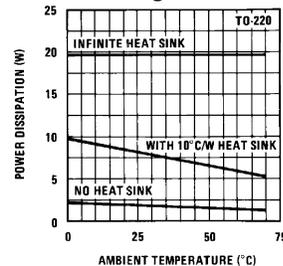
- (1) All characteristics are measured with a $0.22\text{ }\mu\text{F}$ capacitor from input to ground and a $0.1\text{ }\mu\text{F}$ capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques ($t_w \leq 10\text{ ms}$, duty cycle $\leq 5\%$). Output voltage changes due to changes in internal temperature must be taken into account separately.

Typical Performance Characteristics

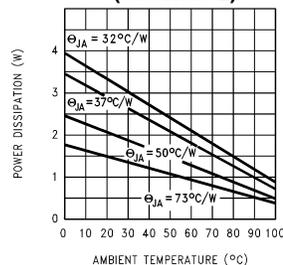
Maximum Average Power Dissipation



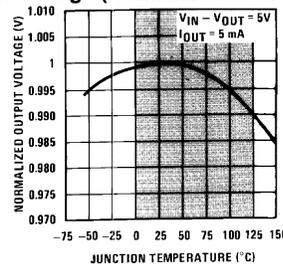
Maximum Average Power Dissipation



Maximum Power Dissipation (TO-263)
(See Note 2)

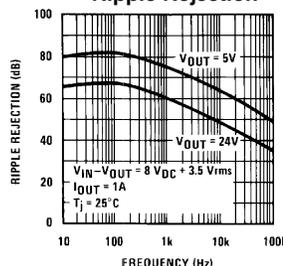


Output Voltage (Normalized to 1V at $T_J = 25^\circ\text{C}$)

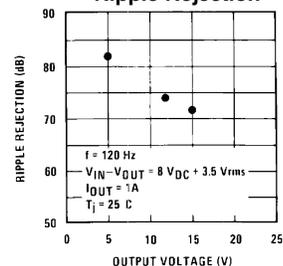


Note: Shaded area refers to LM340A/LM340, LM7805C, LM7812C and LM7815C.

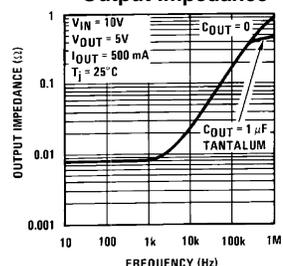
Ripple Rejection



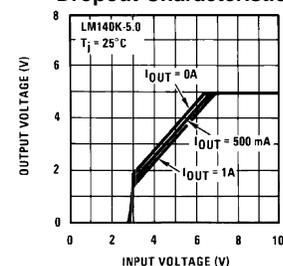
Ripple Rejection



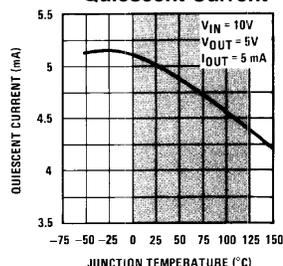
Output Impedance



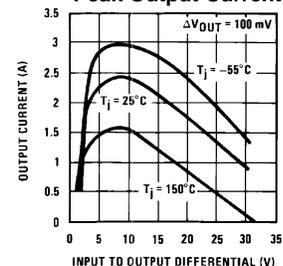
Dropout Characteristics



Quiescent Current

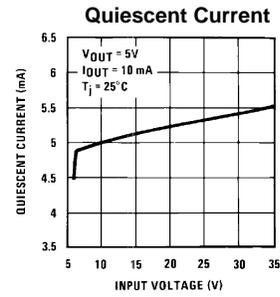
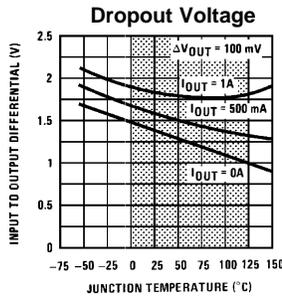


Peak Output Current

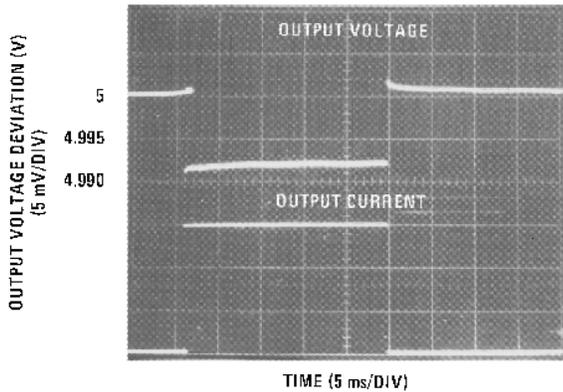


Note: Shaded area refers to LM340A/LM340, LM7805C, LM7812C and LM7815C.

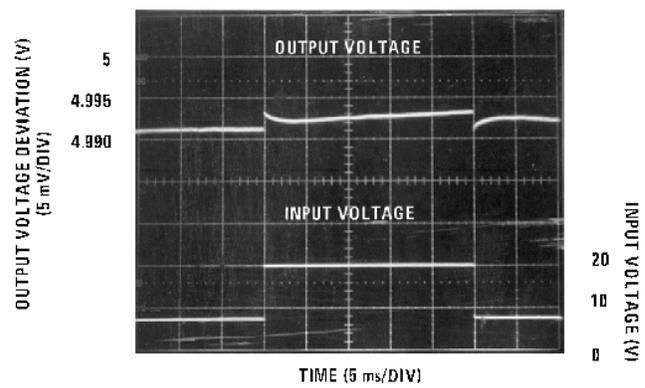
Typical Performance Characteristics (continued)



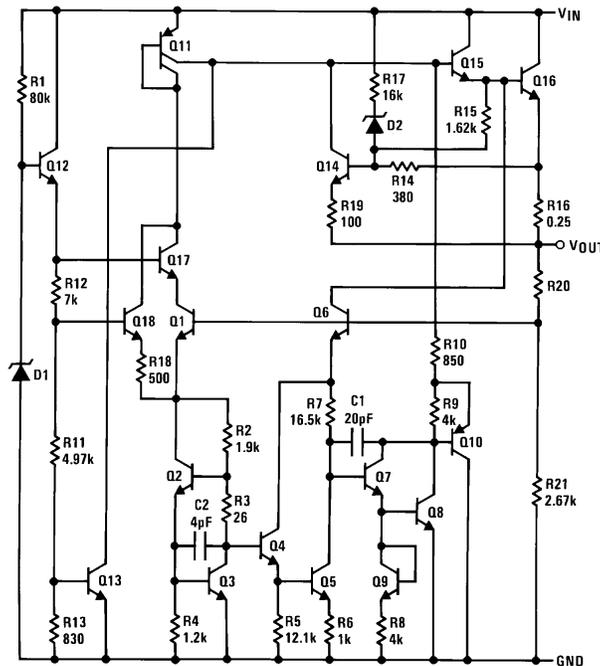
Line Regulation
140AK-5.0, $I_{OUT} = 1A$, $T_A = 25^\circ C$



Line Regulation
140AK-5.0, $V_{IN} = 10V$, $T_A = 25^\circ C$



Equivalent Schematic



Application Hints

The LM340/LM78XX series is designed with thermal protection, output short-circuit protection and output transistor safe area protection. However, as with *any* IC regulator, it becomes necessary to take precautions to assure that the regulator is not inadvertently damaged. The following describes possible misapplications and methods to prevent damage to the regulator.

SHORTING THE REGULATOR INPUT

When using large capacitors at the output of these regulators, a protection diode connected input to output (Figure 9) may be required if the input is shorted to ground. Without the protection diode, an input short will cause the input to rapidly approach ground potential, while the output remains near the initial V_{OUT} because of the stored charge in the large output capacitor. The capacitor will then discharge through a large internal input to output diode and parasitic transistors. If the energy released by the capacitor is large enough, this diode, low current metal and the regulator will be destroyed. The fast diode in Figure 9 will shunt most of the capacitors discharge current around the regulator. Generally no protection diode is required for values of output capacitance $\leq 10 \mu\text{F}$.

RAISING THE OUTPUT VOLTAGE ABOVE THE INPUT VOLTAGE

Since the output of the device does not sink current, forcing the output high can cause damage to internal low current paths in a manner similar to that just described in the "Shorting the Regulator Input" section.

REGULATOR FLOATING GROUND (Figure 10)

When the ground pin alone becomes disconnected, the output approaches the unregulated input, causing possible damage to other circuits connected to V_{OUT} . If ground is reconnected with power "ON", damage may also occur to the regulator. This fault is most likely to occur when plugging in regulators or modules with on card regulators into powered up sockets. Power should be turned off first, thermal limit ceases operating, or ground should be connected first if power must be left on.

TRANSIENT VOLTAGES

If transients exceed the maximum rated input voltage of the device, or reach more than 0.8V below ground and have sufficient energy, they will damage the regulator. The solution is to use a large input capacitor, a series input breakdown diode, a choke, a transient suppressor or a combination of these.

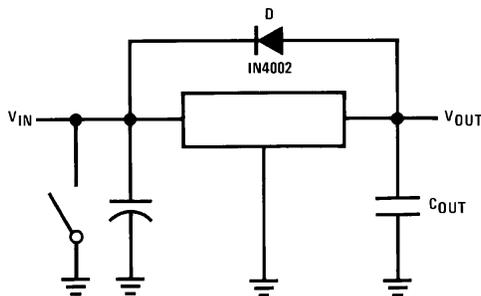


Figure 9. Input Short

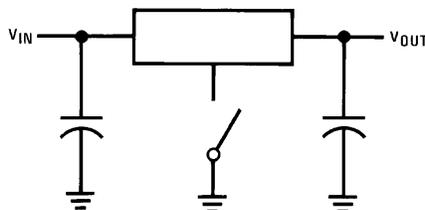


Figure 10. Regulator Floating Ground

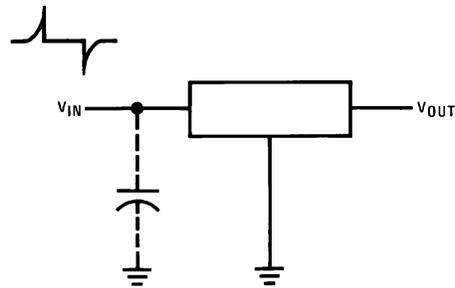


Figure 11. Transients

When a value for $\theta_{(H-A)}$ is found using the equation shown, a heatsink must be selected that has a value that is less than or equal to this number.

$\theta_{(H-A)}$ is specified numerically by the heatsink manufacturer in this catalog, or shown in a curve that plots temperature rise vs power dissipation for the heatsink.

HEATSINKING TO-263 AND SOT-223 PACKAGE PARTS

Both the TO-263 ("S") and SOT-223 ("MP") packages use a copper plane on the PCB and the PCB itself as a heatsink. To optimize the heat sinking ability of the plane and PCB, solder the tab of the plane.

shows for the TO-263 the measured values of $\theta_{(J-A)}$ for different copper area sizes using a typical PCB with 1 ounce copper and no solder mask over the copper area used for heatsinking.

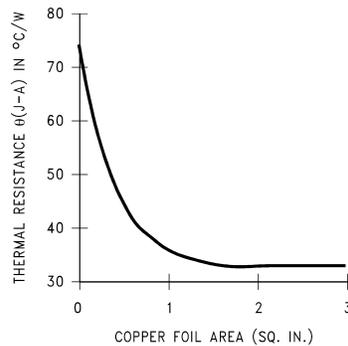


Figure 12. $\theta_{(J-A)}$ vs Copper (1 ounce) Area for the TO-263 Package

As shown in the figure, increasing the copper area beyond 1 square inch produces very little improvement. It should also be observed that the minimum value of $\theta_{(J-A)}$ for the TO-263 package mounted to a PCB is 32 $^{\circ}\text{C}/\text{W}$.

As a design aid, [Figure 13](#) shows the maximum allowable power dissipation compared to ambient temperature for the TO-263 device (assuming $\theta_{(J-A)}$ is 35 $^{\circ}\text{C}/\text{W}$ and the maximum junction temperature is 125 $^{\circ}\text{C}$).

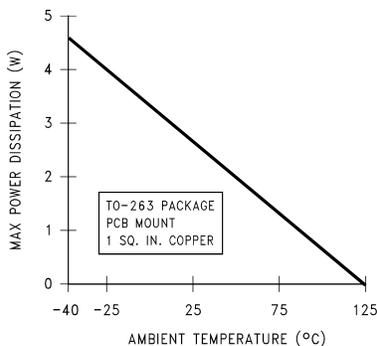


Figure 13. Maximum Power Dissipation vs T_{AMB} for the TO-263 Package

Figure 14 Figure 15 show the information for the SOT-223 package. Figure 14 assumes a $\theta_{(J-A)}$ of 74°C/W for 1 ounce copper and 51°C/W for 2 ounce copper and a maximum junction temperature of 125°C.

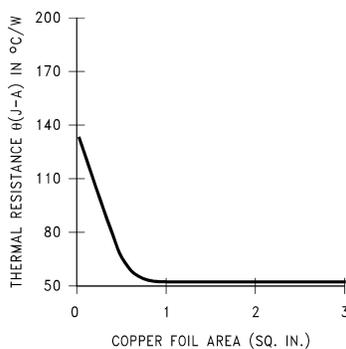


Figure 14. $\theta_{(J-A)}$ vs Copper (2 ounce) Area for the SOT-223 Package

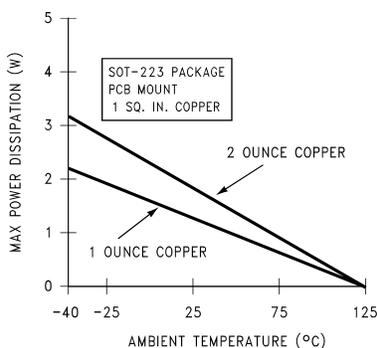
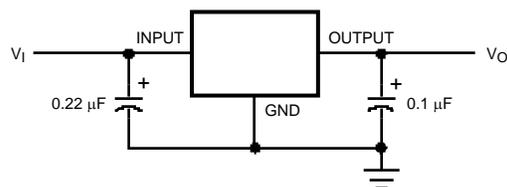


Figure 15. Maximum Power Dissipation vs T_{AMB} for the SOT-223 Package

Please see AN-1028 for power enhancement techniques to be used with the SOT-223 package.

Typical Applications

Figure 16. Fixed Output Regulator



Note: Bypass capacitors are recommended for optimum stability and transient response, and should be located as close as possible to the regulator.

Figure 17. High Input Voltage Circuits

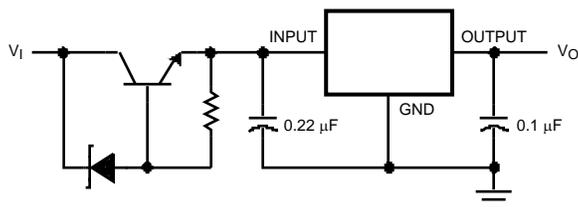
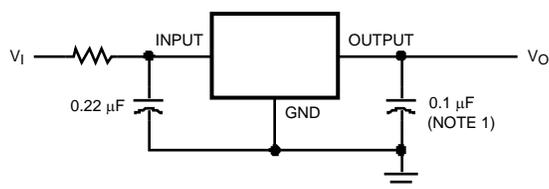
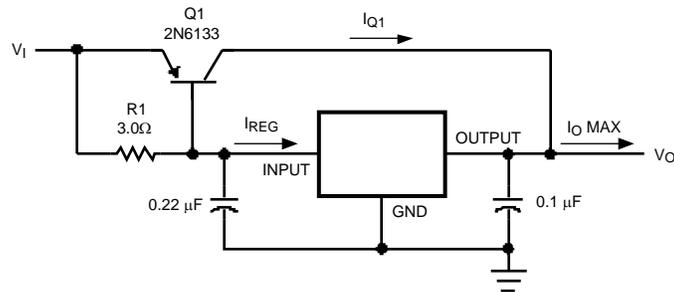


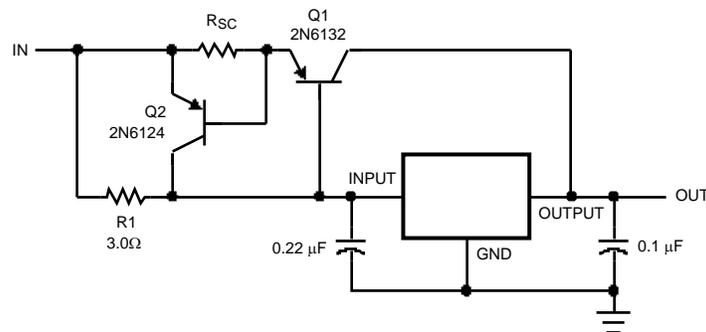
Figure 18. High Current Voltage Regulator



$$\beta(Q1) \geq \frac{I_{O\ Max}}{I_{REG\ Max}}$$

$$R1 = \frac{0.9}{I_{REG}} = \frac{\beta(Q1) V_{BE}(Q1)}{I_{REG\ Max} (\beta + 1) - I_{O\ Max}}$$

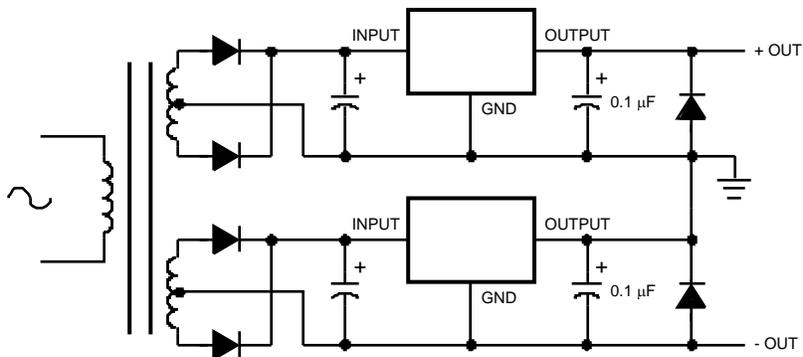
Figure 19. High Output Current, Short Circuit Protected



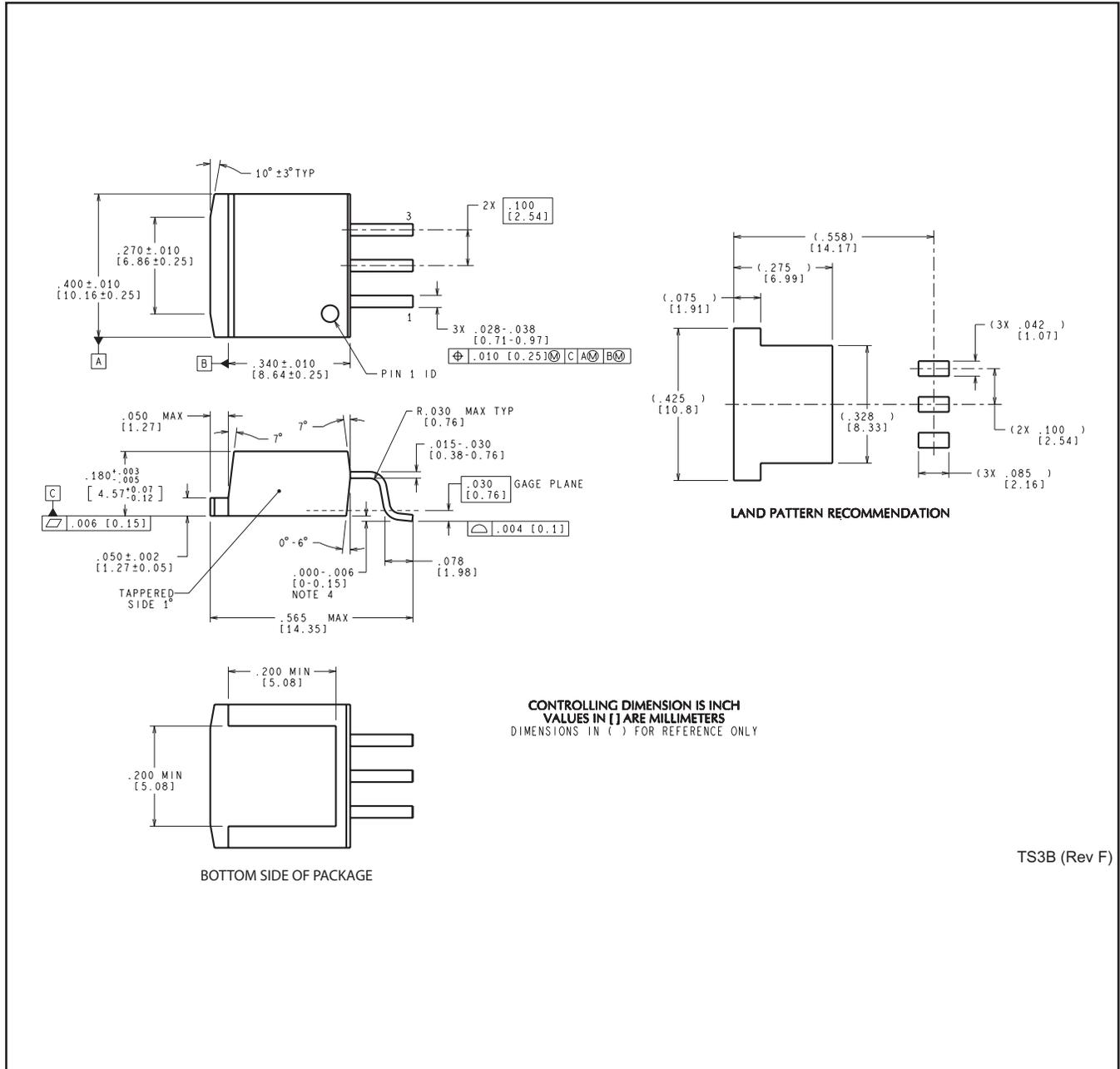
$$R_{SC} = \frac{0.8}{I_{SC}}$$

$$R1 = \frac{\beta V_{BE}(Q1)}{I_{REG\ Max} (\beta + 1) - I_{O\ Max}}$$

Figure 20. Positive and Negative Regulator



KTT0003B



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
LM340AT-5.0	ACTIVE	TO-220	NDE	3	45	TBD	CU SNPB	Level-1-NA-UNLIM	
LM340AT-5.0/NOPB	ACTIVE	TO-220	NDE	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-1-NA-UNLIM	
LM340K-5.0	ACTIVE	TO-3	NDS	2	50	TBD	POST-PLATE	Level-1-NA-UNLIM	
LM340K-5.0/NOPB	ACTIVE	TO-3	NDS	2	50	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	
LM340MP-5.0	ACTIVE	SOT-223	DCY	4	1000	TBD	CU SNPB	Level-1-260C-UNLIM	
LM340MP-5.0/NOPB	ACTIVE	SOT-223	DCY	4	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LM340MPX-5.0/NOPB	ACTIVE	SOT-223	DCY	4	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LM340S-12/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	
LM340S-5.0	ACTIVE	DDPAK/ TO-263	KTT	3	45	TBD	CU SNPB	Level-3-235C-168 HR	
LM340S-5.0/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	
LM340SX-12	ACTIVE	DDPAK/ TO-263	KTT	3	500	TBD	CU SNPB	Level-3-235C-168 HR	
LM340SX-12/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	
LM340SX-5.0	ACTIVE	DDPAK/ TO-263	KTT	3	500	TBD	CU SNPB	Level-3-235C-168 HR	
LM340SX-5.0/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	
LM340T-12	ACTIVE	TO-220	NDE	3	45	TBD	CU SNPB	Level-1-NA-UNLIM	
LM340T-12/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	
LM340T-15	ACTIVE	TO-220	NDE	3	45	TBD	CU SNPB	Level-1-NA-UNLIM	
LM340T-15/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	
LM340T-5.0	ACTIVE	TO-220	NDE	3	45	TBD	CU SNPB	Level-1-NA-UNLIM	
LM340T-5.0/LB01	ACTIVE	TO-220	NDG	3	45	TBD	CU SNPB	Level-3-235C-168 HR	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
LM340T-5.0/LF01	ACTIVE	TO-220	NDG	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-4-260C-72 HR	
LM340T-5.0/NOPB	ACTIVE	TO-220	NDE	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-1-NA-UNLIM	
LM7805CT	ACTIVE	TO-220	NDE	3	45	TBD	CU SNPB	Level-1-NA-UNLIM	
LM7805CT/NOPB	ACTIVE	TO-220	NDE	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-1-NA-UNLIM	
LM7812CT	ACTIVE	TO-220	NDE	3	45	TBD	CU SNPB	Level-1-NA-UNLIM	
LM7812CT/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	
LM7815CT	ACTIVE	TO-220	NDE	3	45	TBD	CU SNPB	Level-1-NA-UNLIM	
LM7815CT/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

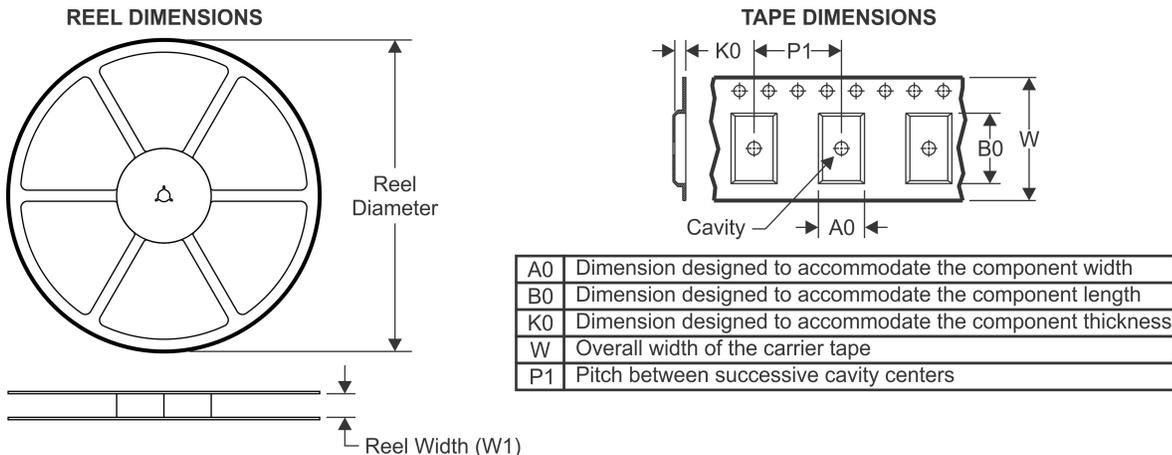
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

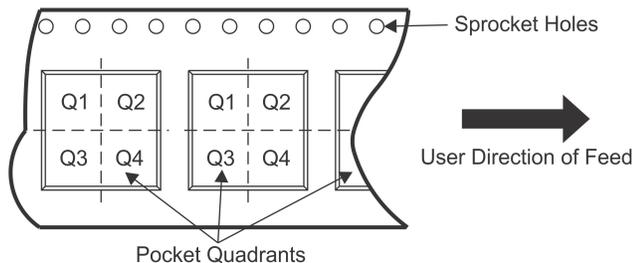
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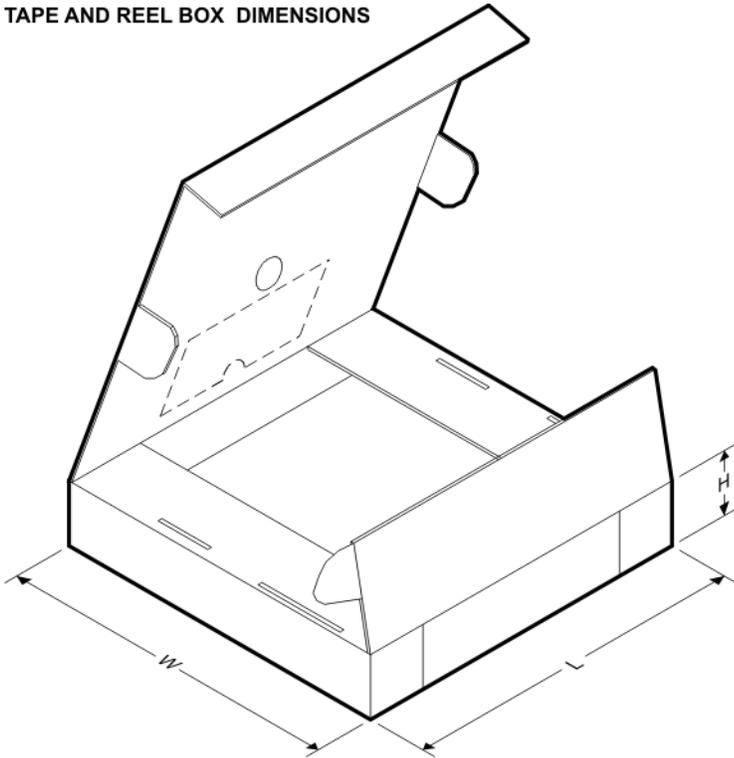


QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

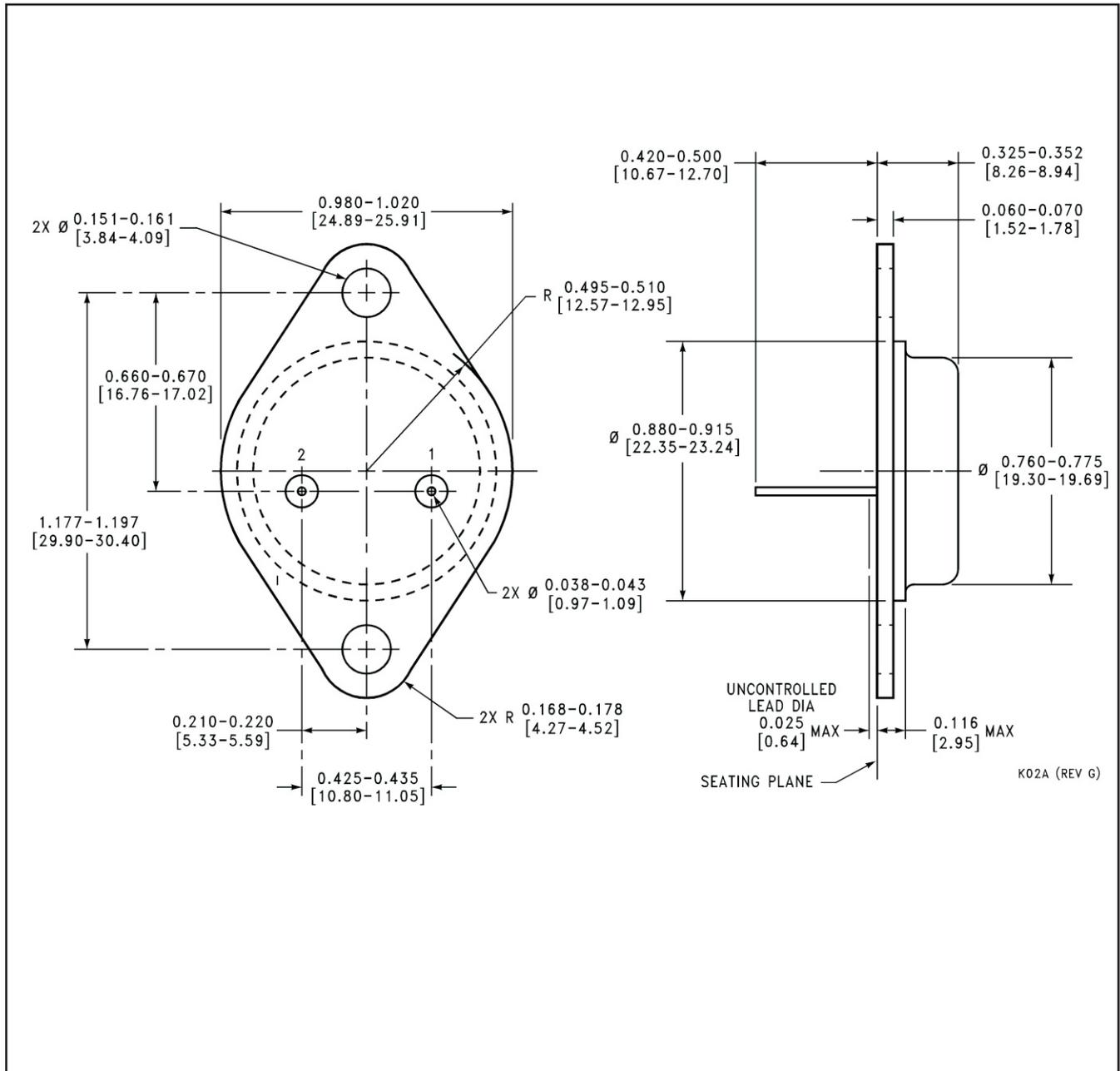
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LM340MP-5.0	SOT-223	DCY	4	1000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM340MP-5.0/NOPB	SOT-223	DCY	4	1000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM340MPX-5.0/NOPB	SOT-223	DCY	4	2000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM340SX-12	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM340SX-12/NOPB	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM340SX-5.0	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM340SX-5.0/NOPB	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2

TAPE AND REEL BOX DIMENSIONS


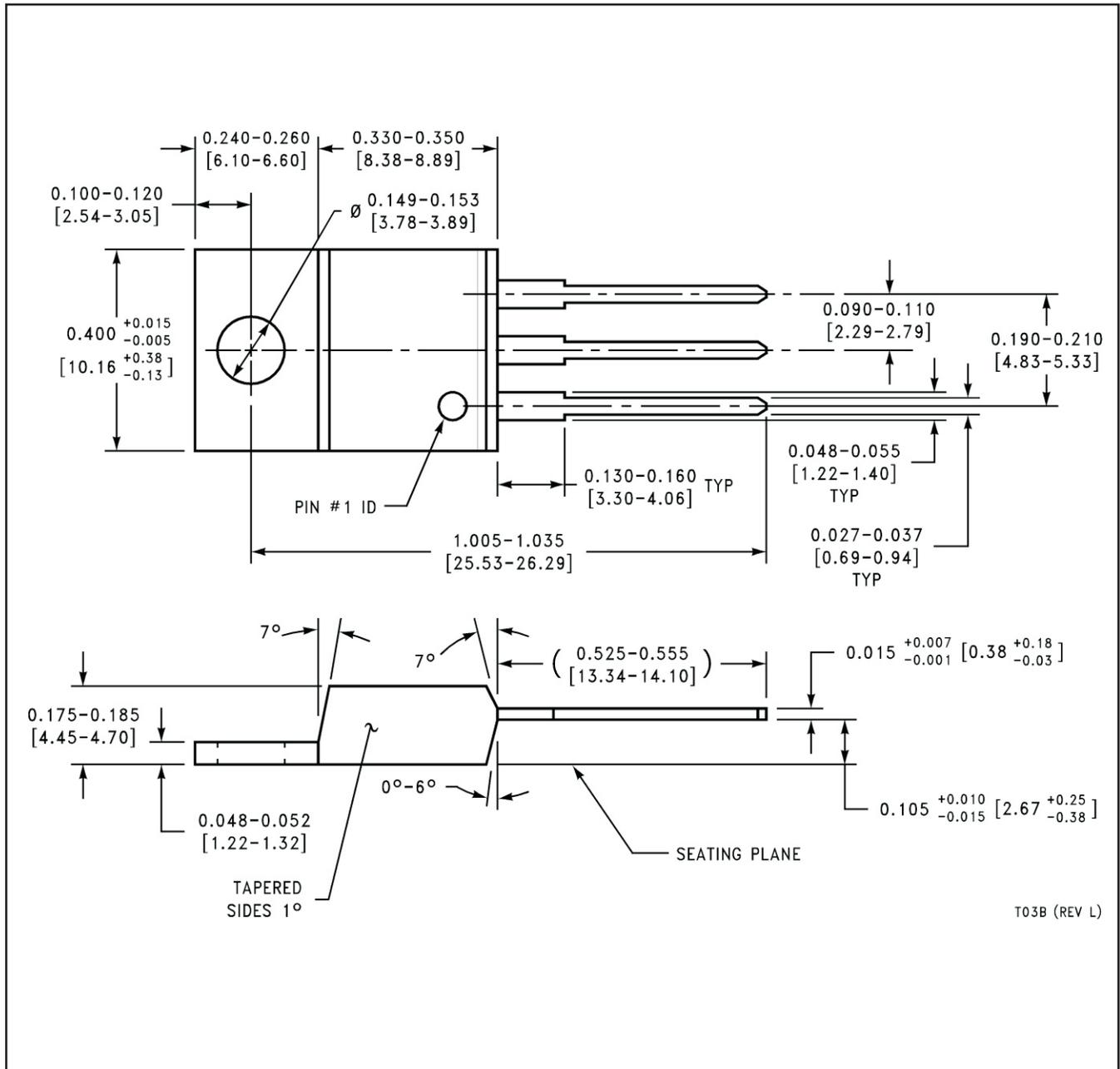
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM340MP-5.0	SOT-223	DCY	4	1000	349.0	337.0	45.0
LM340MP-5.0/NOPB	SOT-223	DCY	4	1000	349.0	337.0	45.0
LM340MPX-5.0/NOPB	SOT-223	DCY	4	2000	354.0	340.0	35.0
LM340SX-12	DDPAK/TO-263	KTT	3	500	358.0	343.0	63.0
LM340SX-12/NOPB	DDPAK/TO-263	KTT	3	500	358.0	343.0	63.0
LM340SX-5.0	DDPAK/TO-263	KTT	3	500	358.0	343.0	63.0
LM340SX-5.0/NOPB	DDPAK/TO-263	KTT	3	500	358.0	343.0	63.0

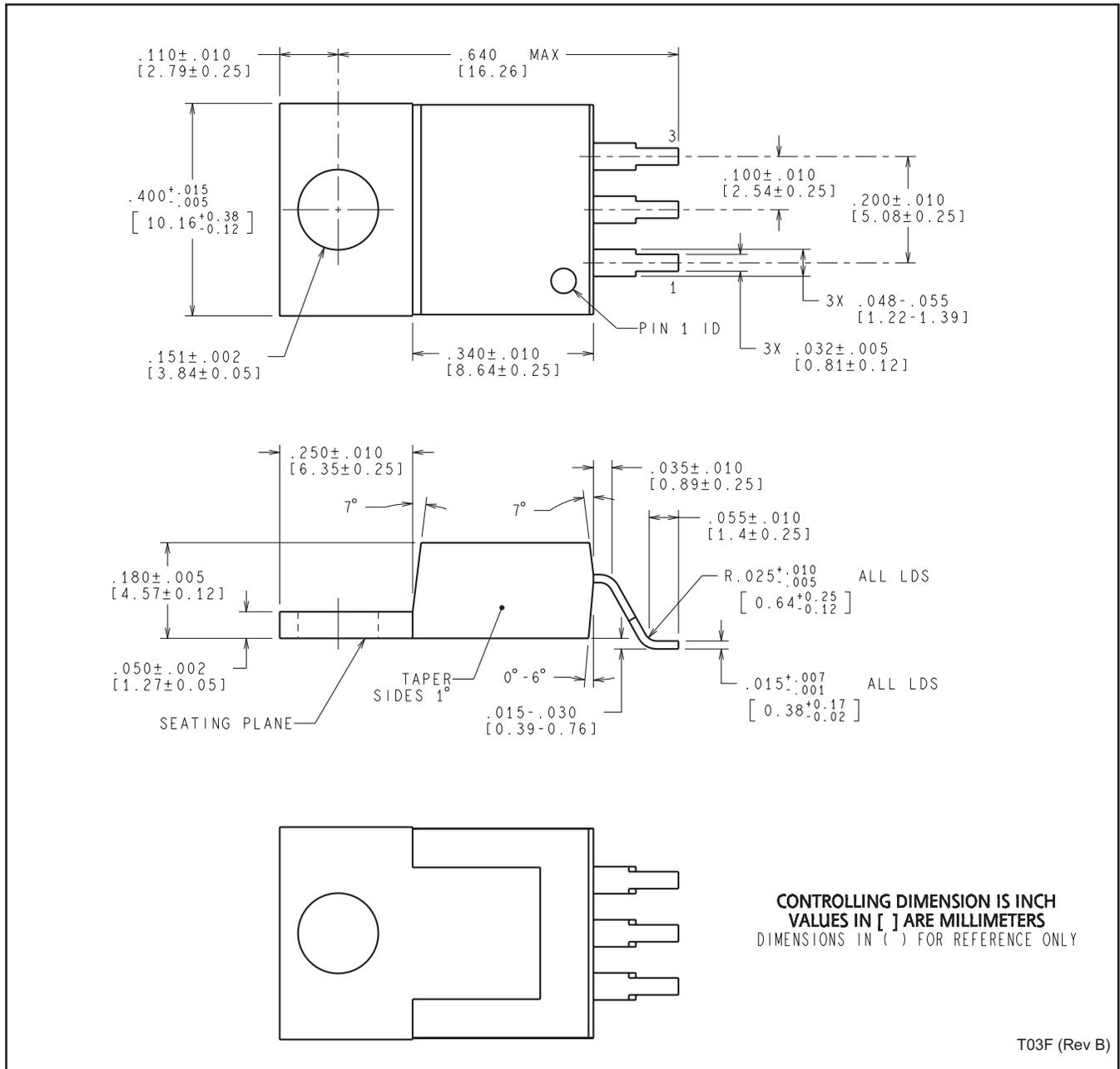
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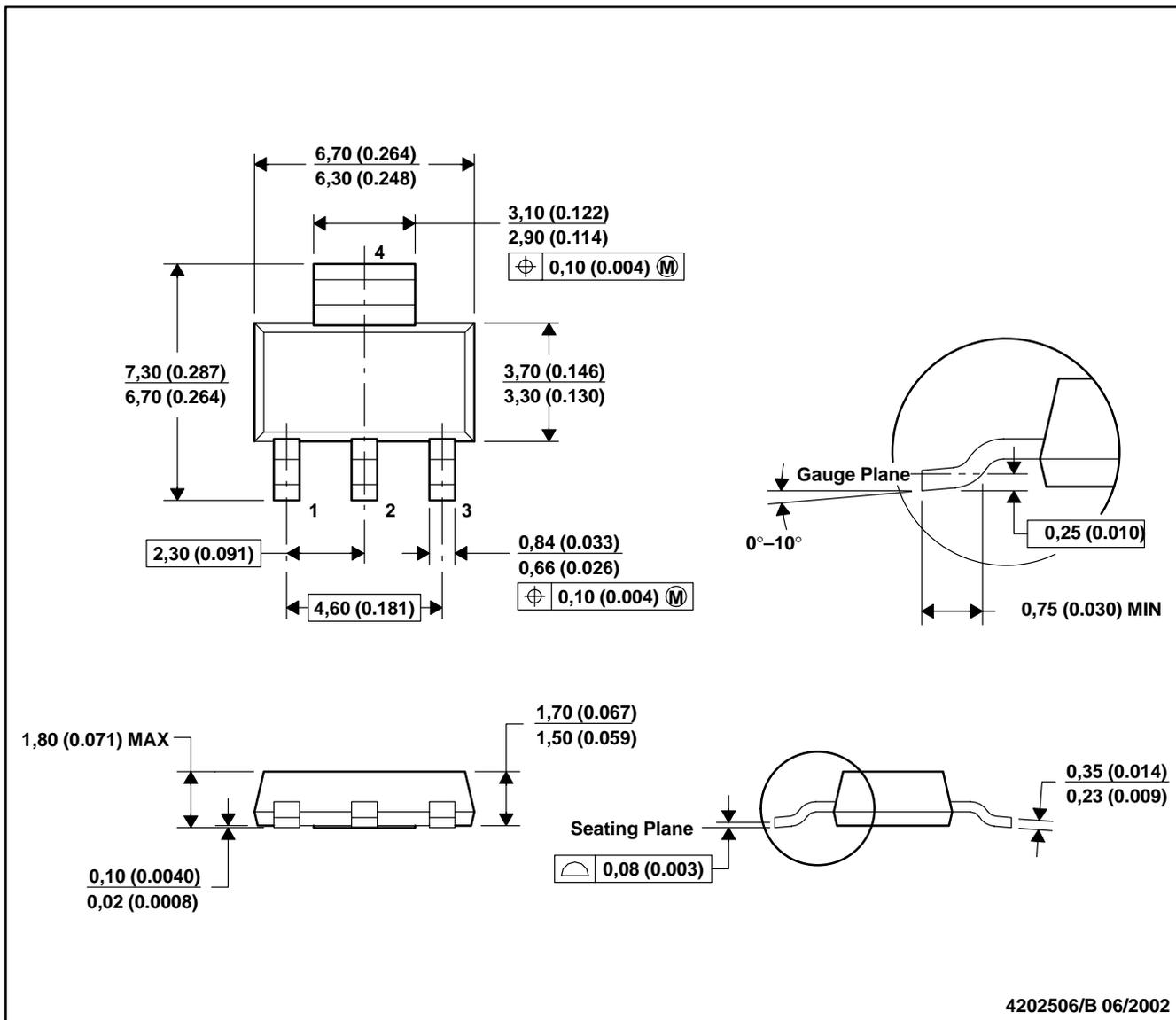


NDG0003F



DCY (R-PDSO-G4)

PLASTIC SMALL-OUTLINE



- NOTES: A. All linear dimensions are in millimeters (inches).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion.
 D. Falls within JEDEC TO-261 Variation AA.

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